

Code No: R05320402

**Set No. 1**

**III B.Tech II Semester Regular Examinations, Apr/May 2008**  
**VLSI DESIGN**

( Common to Electronics & Communication Engineering, Bio-Medical  
 Engineering and Electronics & Telematics)

Time: 3 hours

Max Marks: 80

**Answer any FIVE Questions**  
**All Questions carry equal marks**

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1. Describe the two commonly used methods for obtaining integrated capacitor. [16]
2. (a) Explain various regions of CMOS inverter transfer characteristics.  
 (b) For a CMOS inverter, calculate the shift in the transfer characteristic curve when  $\beta_n/\beta_p$  ratio is varied from 1/1 to 10/1. [8+8]
3. (a) what is a stick diagram? Draw the stick diagram and layout for a CMOS inverter.  
 (b) What are the effects of scaling on  $V_t$ ?  
 (c) What are design rules? Why is metal-metal spacing larger than poly-poly spacing. [8+4+4]
4. Calculate the rise time and fall time of the CMOS inverter  $(W/L)_n=6$  and  $(W/L)_p=8$ ,  $K'_n=150\mu\text{ A/V}^2$ ,  $V_{tn}=0.7\text{V}$ ,  $K'_p=32\mu\text{ A/V}^2$ ,  $V_{tp}=-0.85\text{V}$ ,  $V_{DD}=3.3\text{V}$ . Total output capacitance =150 fF. [16]
5. (a) Explain the CMOS system design based on the data path operators with a suitable example.  
 (b) Draw and explain the basic Memory- chip architecture. [8+8]
6. (a) Draw the typical standard-cell structure showing low-power cell and explain it.  
 (b) Sketch a diagram for two input XOR using PLA and explain its operation with the help of truth table. [8+8]
7. (a) Write a VHDL Program for a divide-by-3 counter with suitable state diagram.  
 (b) Compare all available design verification tools. [8+8]
8. (a) Explain how an improved layout can be reduced faults in CMOS circuits.  
 (b) Explain how a pseudo random sequence generator may be used to test a 16-bit data path. How would the outputs be collected and checked. [6+10]

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1. With neat sketches, explain in detail, all the steps involved in electron lithography process. [16]
2. (a) Explain nMOS inverter and latch up in CMOS circuits?  
(b) Draw the nMOS transistor circuit model and explain various components of the model. [8+8]
3. Draw the stick diagram and mask layout for a CMOS two input NOR gate and stick diagram of two input NAND gate. [16]
4. (a) Explain the concept of sheet resistance and apply it to compute the ON resistance ( $V_{DD}$  to GND) of an NMOS inverter having pull up to pull down ratio of 4:1, If n channel resistance is  $R_{n0} = 10^4 \Omega$  per square.  
(b) Calculate the gate capacitance value of  $5\mu\text{m}$  technology minimum size transistor with gate to channel capacitance value is  $4 \times 10^{-4} \text{pF}/\mu\text{m}^2$ . [10+6]
5. (a) Explain the CMOS system design based on the data path operators with a suitable example.  
(b) Draw and explain the basic Memory- chip architecture. [8+8]
6. (a) What are the characteristics of 22V10 PAL CMOS device and draw its I/O structure.  
(b) Explain any one chip architecture that used the antifuse and give its advantages. [8+8]
7. (a) What are the different types of operators used in VHDL? Give some examples using this.  
(b) Compare the Circuit-level, Logic-level, switch-level and Timing simulations. [8+8]
8. (a) compare functionality test and manufacturing test.  
(b) What type of testing techniques are suitable for the following:
  - i. Memories
  - ii. Random logic
  - iii. Data path.
 (c) How IDDQ testing is used to test the bridge faults? [5+6+5]

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1. (a) What is Moore's law? Explain its relevance with respect to evolution of IC Technology.
- (b) What is the size of silicon wafer used for manufacturing state-of-the art VLSI ICs?
- (c) What is the minimum feature size of current commercial VLSI devices? [8+4+4]
2. Compare the relative merits of three different forms of pull up for an inverter circuits. What is the best choice for realization in
  - (a) nMOS technology
  - (b) CMOS technology. [16]
3. Draw the stick diagram and a translated mask layout for nMOS inverter circuit. [16]
4. Describe three sources of wiring capacitances. Explain the effect of wiring capacitance on the performance of a VLSI circuit. [16]
5. (a) Compare the different types of CMOS subsystem Multipliers.
- (b) Design a schematic for an 8-word  $\times$  2-bit NAND ROM that serves a lookup table to implement a full adder. [8+8]
6. (a) Explain the methods of programming of PAL CMOS device.
- (b) Draw and explain the architecture of an FPGA . [8+8]
7. (a) What are the different data types available in VHDL and how they are indicated?
- (b) Write a VHDL program for a 4-bit Counter with Asynchronous reset. [8+8]
8. (a) Draw the basic structure of parallel scan and explain how it reduces the long scan chains.
- (b) Draw the state diagram of TAP Controller and explain how it provides the control signals for test data and instruction register. [8+8]

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1. Explain the following:
  - (a) Thermal oxidation technique
  - (b) Kinetics of thermal oxidation. [8+8]
2. (a) Explain the operation of BiCMOS inverter? Clearly specify its characteristics.
  - (b) Explain how the BiCMOS inverter performance can be improved. [8+8]
3. Explain the following
  - (a) Double metal MOS process rules.
  - (b) Design rules for P- well CMOS process. [8+8]
4. (a) Define and explain the following:
  - i. Sheet resistance concept applied to MOS transistors and inverters.
  - ii. Standard unit of capacitance.
  - (b) Explain the requirement and functioning of a delay unit. [4+4+8]
5. (a) Draw the schematic for tiny XOR gate and explain its operation.
  - (b) Draw the circuit diagram for 4-by-4 barrel shifter using complementary transmission gates and explain its shifting operation. [8+8]
6. (a) Explain the function of 4:1 Mux in PAL CMOS device with the help of I/O structure.
  - (b) Explain how the pass transistors are used to connect wire segments for the purpose of FPGA programming. [8+8]
7. (a) What are the advantages of Hardware Description Languages and give some examples?
  - (b) Explain the different types of simulators used to predict and verify the performance of given circuit. [8+8]
8. (a) Draw the basic structure of parallel scan and explain how it reduces the long scan chains.
  - (b) Draw the state diagram of TAP Controller and explain how it provides the control signals for test data and instruction register. [8+8]

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